

WKS50WV009-WCT

PRODUCT: TFT TOUCH MODULE

MODULE NO. : WKS50WV009-WCT

SUPPLIER: WKS Technology Co., LTD

DATE: Dec 11, 2018

SPECIFICATION

Revision: 0.0

WKS50WV009-WCT

This module uses ROHS material

This specification may change without prior notice in order to improve performance or quality. Please contact WKS R&D department for updated specification and product status before design for this product or release of this order.

WRITTEN BY	CHECKED BY	APPROVED BY
Jason	Eric	Henry



WKS50WV009-WCT

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
0.0	2018-12-11	First release	Preliminary



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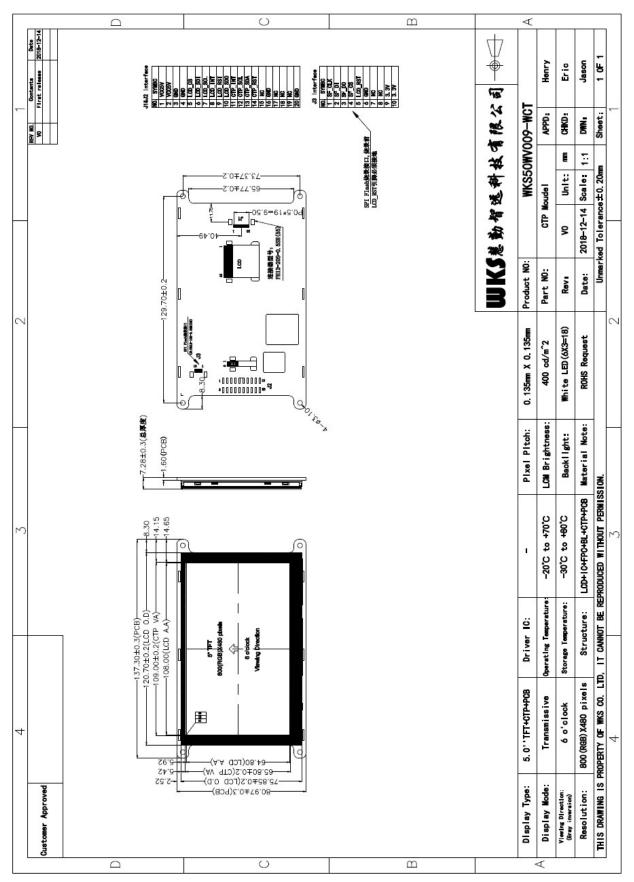


1, GENERAL INFORMATION

Item of general information		Contents	Unit	
LCD Display Size (Diagonal)		5.0		
Module Structure	LCD I	Display + CTP Touch + PCB	-	
LCD Display Type		TFT/TRANSMISSIVE	-	
LCD Display Mode		Normally White	-	
Recommended Viewing Direction		12	o'clock	
Gray inversion Direction		6	o'clock	
Module size (W×H×T)		137.30×80.97×7.28		
Active area (W×H)		108.00×64.80	mm	
Number of pixels (Resolution)		800RGB×480	pixel	
Pixel pitch (W×H)		0.135×0.135	mm	
LCD Driver IC		-	-	
	LCD	3 wire SPI interface	-	
Module Interface Type	СТР	I2C interface	_	
Module Input voltage	5.0V		V	
Module Power consumption	-		mW	
Color Numbers	16.7M		-	
Backlight Type		White LED	-	

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2, EXTERNAL DIMENSIONS





3, ABSOLUTE MAXIMUM RATINGS

Parameter of absolute maximum ratings	Symbol	Min	Max	Unit
Operating temperature	Тор	-20	70	$^{\circ}\!C$
Storage temperature	Tst	-30	80	°C
Humidity	RH	-	90%(Max 60°C)	RH

Note: Absolute maximum ratings means the product can withstand short-term, not more than 120 hours. If the product is a long time to withstand these conditions, the life time would be shorter.

4、 ELECTRICAL CHARACTERISTICS(DC CHARACTERISTICS)

Parameter of DC characteristics	Symbol	Min.	Typ.	Max.	Unit
PCB operating voltage	VCC5V	-	5.0	-	V
LCD I/O operating voltage	VDD	3.0	3.3	3.6	V
Input voltage 'H' level	VIH	2	-	3.6	V
Input voltage 'L' level	VIL	-0.3	-	0.8	V
Output voltage 'H' level	VOH	2.4	-	-	V
Output voltage 'L' level	VOL	-	-	0.4	V

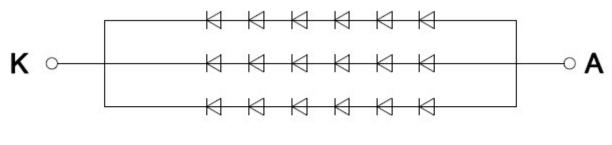


5、 BACKLIGHT CHARACTERISTICS

Item of backlight characteristics	Symbol	Min.	Typ.	Max.	Unit	Remark
Forward Voltage	Vf	17.4	18.6	19.8	V	Note1
Forward Current	If	-	60	-	mA	-
Number of LED	-	-	6*3=18	-	Piece	-
LED Connection mode	P/S	-	Serial/Parallel	-	-	-
Lifetime of LED	-	-	10000	-	hour	Note2

Note:

- ➢ Note1: The LED Supply Voltage is defined by the number of LED at Ta=25℃ and If=60mA.
- ➢ Note2: The LED lifetime define as the estimated time to 50% degradation of initial luminous. The LED lifetime could be decreased if operating If is larger than 60mA.
- *Backlight circuit:*



VF=18.6V±1.2V;IF=60mA(Typ.)



6, CTP CHARACTERISTICS

Item of CTP characteristics	Specification	Unit	Remark
Panel Type	Glass Cover + Glass Sensor	-	-
Driver IC	GT5688	-	-
Resolution	800 imes 480	pixel	-
Surface Hardness	<i>≥</i> 6H	-	-
Transparency	>82%	-	-
Driver IC	_	-	-
Interface Type	I2C	-	-
Support Points	5(Max)	-	-
Sampling Rate	20~100	Hz	-
Supply voltage	3.3	V	-



7, ELECTRO-OPTICAL CHARACTERISTICS

Item o electro-op character	otical	Symbol	Condition	Min.	Typ.	Max.	Unit	Remark	Note
Response	time	Tr+Tf	$\theta=0$	-	20	-	ms	FIG 1.	4
Contrast H	Ratio	CR	$\mathcal{A}=0$ $\mathcal{A}=0$	-	350	-	-	<i>FIG 2</i> .	1
Luminance un	iformity	SWHITE	$Ta=25^{\circ}C$	-	80	-	%	<i>FIG 2</i> .	3
Surface Lum	inance	Lv		-	400	-	cd/m2	<i>FIG 2</i> .	2
	White	White x		-	0.317	-		FIG 2.	5
	white	White y		-	0.324	-	_		
	Red	Red x		-	0.633	-			
CIE(x, y)	кеа	Red y	$\theta = 0$	-	0.341	-			
chromaticity	C	Green x	$\mathcal{Q}=0$ $Ta=25^{\circ}C$	-	0.324	-			
	Green	Green y	14 25 0	-	0.551	-			
	ות	Blue x		-	0.153	-			
	Blue	Blue y		-	0.143	-			
	Ø=90(12 o'clock)			-	50	-	deg		
Viewing	Ø=270((6 o'clock)	CD > 10	-	60	-	deg		
angle range	Ø=0(3	o'clock)	$CR \ge 10$	-	65	-	deg	<i>FIG 3</i> .	6
	Ø=180((9 o'clock)		-	65	-	deg		
NTSC ratio		-	-	-	50	-	%	-	-

Note 1. Contrast Ratio (CR) is defined mathematically by the following formula. For more information see FIG 2.:

Contrast Ratio(CR) = Average Surface Luminance with all white pixels(P1,P2,P3,P4,P5,P6,P7,P8,P9) Average Surface Luminance with all black pixels(P1,P2,P3,P4,P5,P6,P7,P8,P9)

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

Lv=Average Surface Luminance with all white pixels (P1,P2,P3,P4,P5,P6,P7,P8,P9)

Note 3. The uniformity in surface luminance (δ WHITE) is determined by measuring

luminance at each test position 1 through 9, and then dividing the maximum luminance of 9 points luminance by minimum luminance of 9 points luminance. For more information see FIG 2.

 $\delta WHITE = \frac{Minimum Surface Luminance with all white pixels (P1, P2, P3, P4, P5, P6, P7, P8, P9)}{Maximum Surface Luminance with all white pixels (P1, P2, P3, P4, P5, P6, P7, P8, P9)}$

Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1.

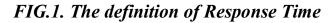
Note 5. CIE (*x*, *y*) *chromaticity*, *The x,y value is determined by screen active area position 5. For more information see FIG 2.*

Note 6. Viewing angle is the angle at which the contrast ratio is greater than a specific value. For TFT module, the specific value of contrast ratio is 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note 7. For Viewing angle and response time testing, the testing data is base on

Autronic-Melchers's ConoScope. Series Instruments. For contrast ratio, Surface Luminance, Luminance uniformity and CIE, the testing data is base on BM-7 photo detector.

Note 8. For TN type TFT transmissive module, Gray scale reverse occurs in the direction of panel viewing angle.



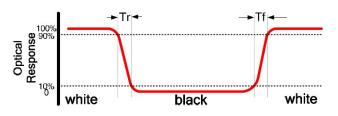


FIG.2. Measuring method for Contrast ratio, surface luminance, Luminance uniformity,

CIE (x, y) chromaticity

A : H/6 ; B : V/6 ;

H,*V* : *Active Area(AA) size*

Measurement instrument: BM-7; Light spot size=5mm, 350mm distance from the LCD surface to detector lens.

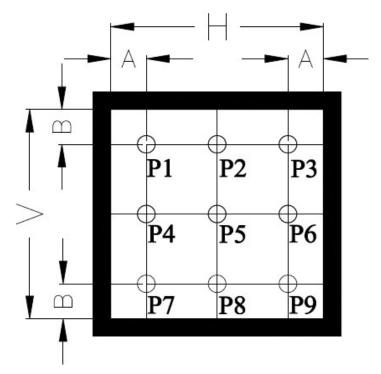
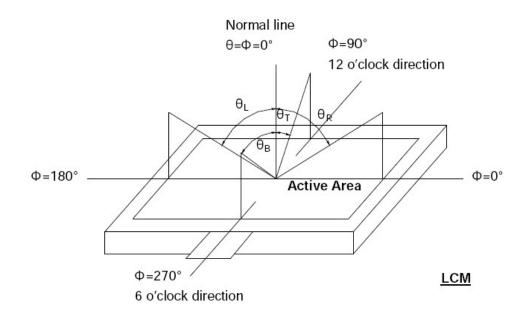


FIG.3. The definition of viewing angle



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8, INTERFACE DESCRIPTION

8.1, J1&J2 Interface Description

<i>N0</i> .	Symbol	I/O	DESCRIPTION
1~2	VCC5V	Power supply	Module Power supply (5V Typ.)
3~4	GND	Power supply	Power ground
5	LCD_CS	Ι	Chip Select pin for 3-wire serial I/F.
6	NC	-	No connection
7	LCD_SCLK	Ι	Clock of 3-wire serial I/F.
8	LCD_INT	0	The interrupt output for host to indicate the status.
9	LCD_RST	Ι	This is an active low Reset pin for LCD.
10	LCD_SDA	I/O	Bi-direction data pin of 3-wire SPI I/F.
11	CTP_INT	0	CTP External interrupt to the host
12	CTP_SCL	Ι	CTP I2C clock input
13	CTP_SDA	I/O	CTP I2C data input and output
14	CTP_RST	Ι	CTP external reset signal, Low is active
15	NC	-	No connection
16	GND	Power supply	Power ground
17	NC	-	No connection
18	NC	-	No connection
19	NC	-	No connection
20	GND	Power supply	Power ground

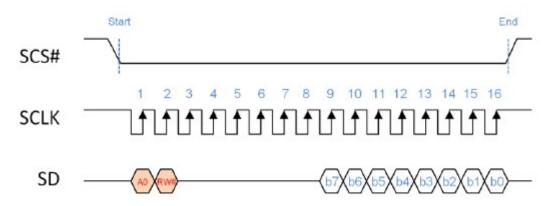


8.3 J3 Interface Description (SPI Flash burning interface)

<i>NO</i> .	Symbol	I/O	DESCRIPTION
1	SF_CLK	Ι	Serial Clock Input
2	SF_DI	Ι	Data Input
3	SF_DO	0	Data output
4	SF_CS	Ι	Chip Select Input
5	LCD_RST	Ι	LCD RESET signal. This pin must be pull low
6	GND	Power supply	Power ground
7	NC	-	No connection
8	NC	-	No connection
9~10	3.3V	Power supply	Power supply for the SPI Flash (3.3V Typ.)

9, INPUT TIMING

9.1, 3-wire SPI Interface



Status Register Read:

- 1. Host drive SCS#(Low) and SCLK (SPI Clock).
- 2. Host drive A0(Low), then drive RW#(High).
- 3. The Driver IC will drive the Data of Status Register ($b7 \sim b0$) at 9th \sim 16th Clock. Then Host will get the content of Status Register.

Write Register's Address:

- 1. Host drive SCS#(Low) and SCLK.
- 2. Host drive A0(Low), then drive RW#(Low).
- 3. Host drive the Register's Address ($b0 \sim b7$) at 9th ~ 16 th Clock to The Driver IC.

Write Data to Register or Memory:

- 1. Host drive SCS#(Low) and SCLK.
- 2. Host drive A0(High), then drive RW#(Low).
- 3. Host drive the Data at 9th ~ 16th Clock to The Driver IC. i.e. Data will be stored in Register or Memory.

Read Register's Data:

- 1. Host drive SCS#(Low) and SCLK.
- 2. Host drive A0(High), then drive RW#(High).

3. The Driver IC will drive the Data of Register at 9th ~ 16th Clock. Then Host will get the content of Register.



10, RELIABILITY TEST CONDITIONS

No.	Test Item	Test Condition
1	High Temperature Storage	80°C/120 hours
2	Low Temperature Storage	-30°C/120 hours
3	High Temperature Operating	70°C/120 hours
4	Low Temperature Operating	-20°C/120 hours
5	Temperature Cycle Storage	-20°C(30min.)~25(5min.)~70°C(30min.)×10cycles

A. Inspection after test:

Inspection after 2~4 hours storage at room temperature, the sample shall be free from

defects:

- *▶* Air bubble in the LCD;
- ➤ Sealleak;
- > Non-display;
- Missing segments;
- Glass crack;
- Current is twice higher than initial value.

B, Remark:

- > The test samples should be applied to only one test item.
- Sample size for each test item is 5~10pcs.
- Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



11, INSPECTION CRITERION

This specification is made to be used as the standard of acceptance/rejection criteria for TFT-LCD/IPS TFT-LCD module product, and this specification is applicable only in the case that the size of module equal to or exceed than 3.5 inch.

11.1 Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC

Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65

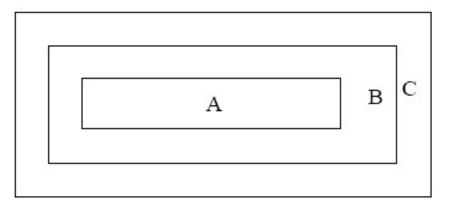
Minor defect: AQL 1.5

11.2 Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within 45 °against perpendicular line. (Normal temperature 20~25 °C and normal humidity 60 $\pm 15\%$ RH)

11.3 Definition of Inspection Item.

A. Definition of inspection zone in LCD.



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Zone A: character/Digit area

Zone B: viewing area except Zone A (Zone A + Zone B=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

B, Definition of some visual defect

	Because of losing all or part function, bad pixel dots appear bright and the
Bright dot	size is more than 50% of one dot in which LCD panel is displaying under
	black pattern.
David de t	Dots appear dark and unchanged in size in which LCD panel is displaying
Dark dot	under pure red, green, blue picture, or pure whiter picture.

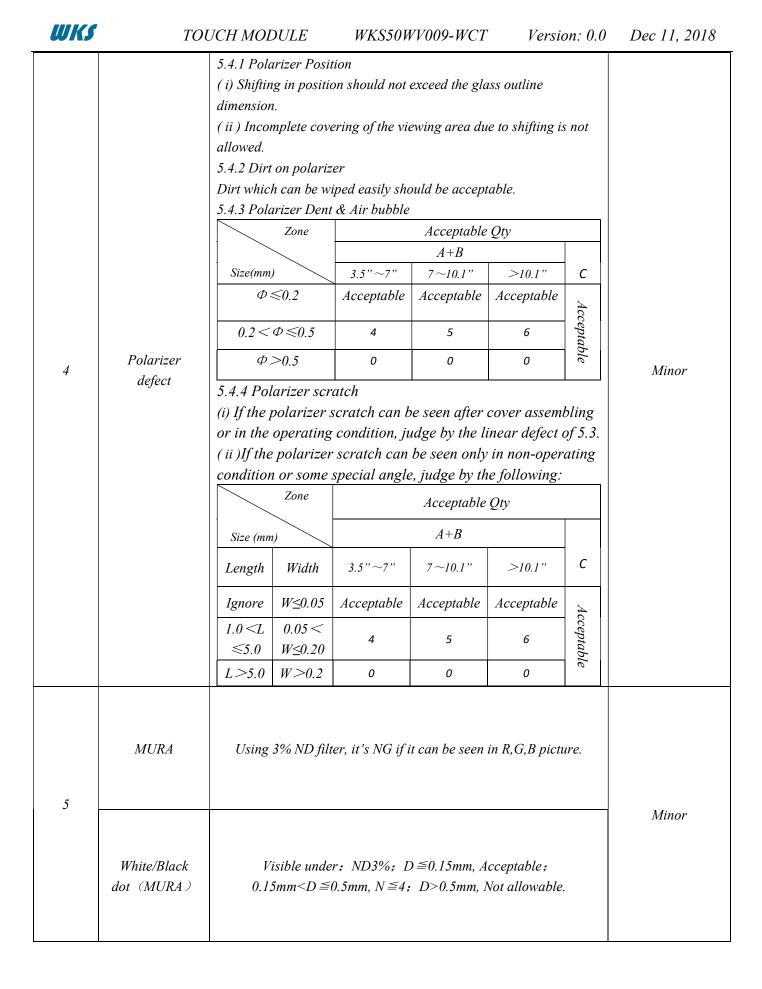
11.4 Major Defect

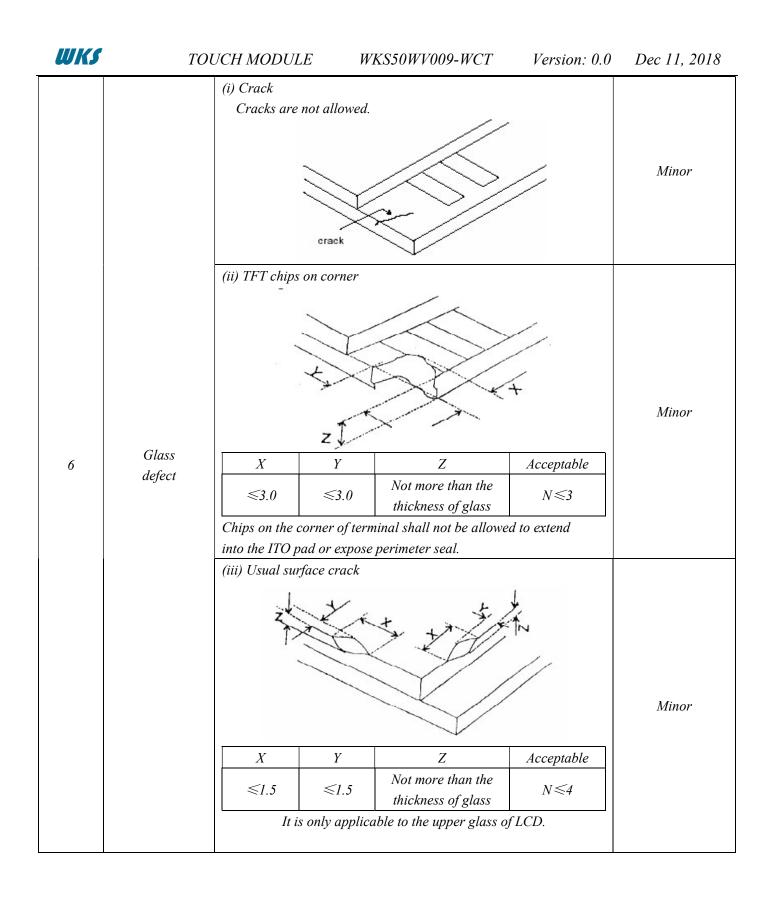
Item No.	Items to be inspected	Inspection standard	Classification of defects
1	Functional defects	 No display Display abnormally Missing vertical, horizontal segment Short circuit Excess power consumption Backlight no lighting, flickering and abnormal lighting 	major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	



11.5 Minor Defect

Item No.	Items to be inspected	Inspection standard							Classification of defects	
		Zone Acceptable Qty								
				F		A+B	27			
	Bright dot				3.5" ~ 7"	~ 7~10.1'	· >10.1 "	С		
		Br	ight pixel do	t	1	2	3			
		D		4	4	4	Acceptable Minor			
1	/dark dot	2bright dots adjace		icent	0	0		0	Minor	
	defect	2dark dots adjac		cent	0	0		0		
		Total i	bright and	dark	5	6	7	le		
			dots							
		Note: Min	Note: Minimum distance between defective dots is more than 5mm;							
		Pixel dots	' function	is norma	l, but bri	ight dots ca	used by foreig	<i>gn</i>		
	material and other reasons are judged by the dot defect of 5.2.									
		Zone Acceptable Qty								
	Dot defect					A+B				
		$ \frac{Size(mm)}{\Phi \leq 0.2} $		3.5"~	3.5"~7" 7~10.1"		>10.1"	С		
				Acceptable		Acceptable .	Acceptable	<u> </u>		
								Acce	Minor	
2		0.2 <	$\Phi \leq 0.5$	4		5	6 0	pta.		
2	$\Phi = (x+y)/2$	Φ>0.5		0		0	o o			
		Note:								
		1. Minimum distance between defective dots is more than 5 mm;								
		2. The quantity of defect is zero in operating condition.								
	Linear defect		Zone Acceptable Qty							
3					1					
		Size (mm)		A+B						
		Length	Width	3.5"~	-7"	7~10.1"	>10.1"	С	Minor	
		Ignore	<i>W</i> ≤0.05	Accepte	able A	cceptable	Acceptable	A		
		$L \leq 5.0$	0.05 <	4		5	6	Acceptable		
			W≤0.1					ptal		
		L>5.0	$W \ge 0.1$	0		0	0	he		
				-						





11.6 Module Cosmetic Criteria

Item No.	Items to be inspected	Inspection Standard	Classification of defects	
1	Difference in Spec.	Not allowable	Major	
2	Pattern peeling	No substrate pattern peeling and floating	Major	
	Soldering defects	No soldering missing	Major	
3		No soldering bridge	Major	
		No cold soldering	Minor	
4	Resist flaw on PCB	Visible copper foil ($\Phi 0.5$ mm or more) on substrate pattern is not allowed	Minor	
5	FPC gold finger	No dirt, breaking, oxidation lead to black	Major	
6	Backlight plastic frame	No deformation, crack, breaking, backlight positioning column breaking, obvious nick.	Minor	
7	Marking printing effect	No dark marking, incomplete, deformation lead to unable to judge	Minor	
8	Accretion of metallic Foreign matter	No accretion of metallic foreign matter (Not exceed $\Phi 0.2mm$)	Minor	
9	Stain	No stain to spoil cosmetic badly	Minor	
10	Plate discoloring	No plate fading, rusting and discoloring	Minor	
11	1. Lead parts	a. Soldering side of PCB Solder to form a 'Filet' all around the lead. Solder should not hide the lead form perfectly.	Minor	
		b. Components side(In case of 'Through Hole PCB') Solder to reach the Components side of PCB.	Minor	
	2. Flat packages	Either 'Toe'(A) or 'Seal'(B)of the lead to be covered by "Filet". Lead form to be assume over Solder.	Minor	
	3. Chips	$(3/2) H \ge h \ge (1/2) H$	Minor	
	4. Solder ball/Solder splash	a. The spacing between solder ball and the conductor or solder pad $h \ge 0.13$ mm. The diameter of solder ball $d \le 0.15$ mm.	Minor	
		b. The quantity of solder balls or solder splashes isn't beyond 5 in 600 mm2.	Minor	
		c. Solder balls/Solder splashes do not violate minimum electrical clearance.	Major	